

Description

The HAO3456 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = 30V I_{D} = 5.8A$

 $R_{DS(ON)}$ < 28m Ω @ V_{GS} =10V

Application

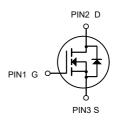
Battery protection

Load switch

Uninterruptible power supply

D iii de g

SOT-23



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
HAO3456	SOT-23	3404 XXXX	3000

Absolute Maximum Ratings (T_A=25°C unless otherwisenoted)

Symbol	Parameter	Limit	Unit
V _{DS}	Drain-Source Voltage	30	V
V _G s	Gate-Source Voltage	±20	V
I _D	Drain Current-Continuous	5.8	Α
Ідм	Drain Current-Pulsed (Note 1)	18.4	Α
P _D	Maximum Power Dissipation	1	W
ТЈ,Тѕтс	Operating Junction and Storage Temperature Range	-55 To 150	°C
Reja	Thermal Resistance,Junction-to-Ambient (Note 2)	125	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0 V , I_D =250 u A	30			V	
$\triangle BV_{DSS}/\triangle T$	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA		0.023		V/°C	
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =4A	22 28		mΩ		
	Static Dialii-Source Off-Nesistance	V _{GS} =4.5V , I _D =3A		26	32	1115.2	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.0	1.5	2.5	V	
$\triangle V_{\text{GS(th)}}$	V _{GS(th)} Temperature Coefficient	VGS-VDS , ID -230UA		-4.2		mV/°C	
Inco	Drain-Source Leakage Current	V_{DS} =24V , V_{GS} =0V , T_J =25 $^{\circ}$ C			1	- uA	
I _{DSS}		V _{DS} =24V , V _{GS} =0V , T _J =55°C			5		
Igss	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =4A		7		S	
R_g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2.3	4.6	Ω	
Qg	Total Gate Charge (4.5V)			5.0	6.9		
Q_{gs}	Gate-Source Charge	V _{DS} =15V , V _{GS} =4.5V , I _D =4A		1.1	2.2	nC	
Q_{gd}	Gate-Drain Charge			2.6	2.8		
$T_{d(on)}$	Turn-On Delay Time			2	4		
Tr	Rise Time	V_{DD} =15V , V_{GS} =10V , R_{G} =3.3 Ω		34.4	62	ns	
$T_{d(off)}$	Turn-Off Delay Time	I _D =4A		13.2	26		
Tf	Fall Time			4.8	9.6		
Ciss	Input Capacitance			420	582		
C_{oss}	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		60	87	pF	
Crss	Reverse Transfer Capacitance			53	71		
ls	Continuous Source Current ^{1,4}	V _G =V _D =0V , Force Current			4.6	Α	
Ism	Pulsed Source Current ^{2,4}	vg-vb-ov , i orce current			18.4	Α	
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V	
t _{rr}	Reverse Recovery Time			8.7		nS	
Q _{rr}	Reverse Recovery Charge	I _F =4A , dl/dt=100A/µs , T _J =25°C		2.3		nC	

Note:

^{1.} The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

^{2.}The data tested by pulsed , pulse width $\, \leqq \,$ 300us , duty cycle $\, \leqq \,$ 2%

^{3.} The power dissipation is limited by 150°C junction temperature

^{4.} The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

Typical Characteristics

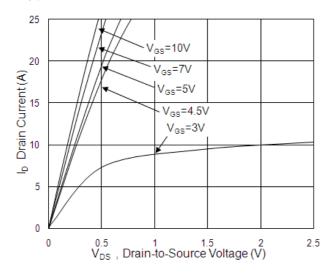


Fig.1 Typical Output Characteristics

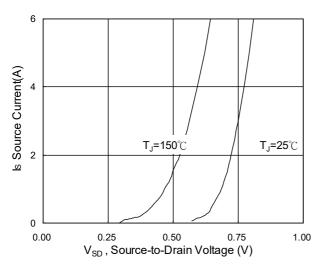


Fig.3 Forward Characteristics Of Reverse

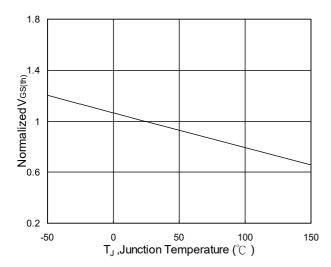


Fig.5 Normalized V_{GS(th)} vs. T_J

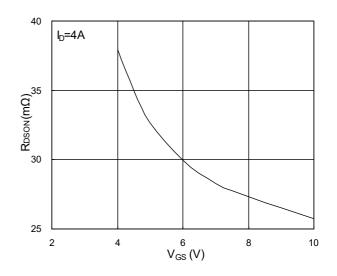


Fig.2 On-Resistance vs. Gate-Source

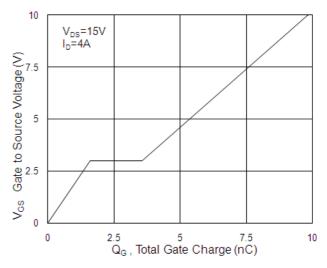


Fig.4 Gate-Charge Characteristics

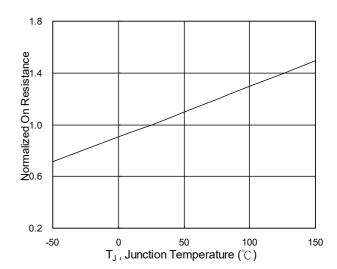
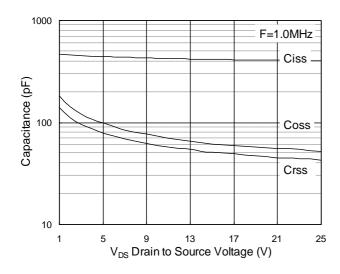


Fig.6 Normalized R_{DSON} vs. T_J



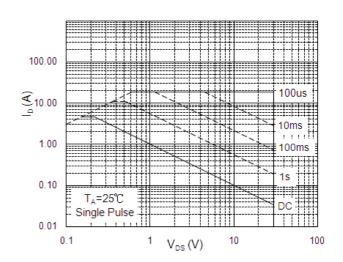


Fig.7 Capacitance

Fig.8 Safe Operating Area

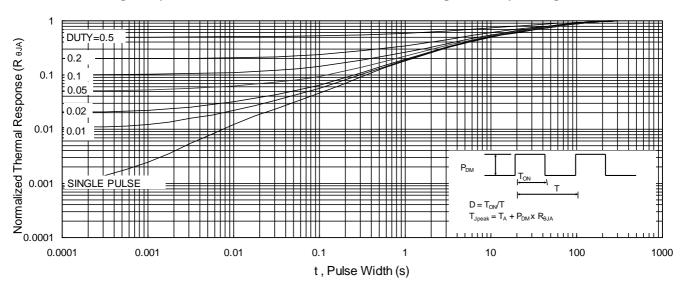


Fig.9 Normalized Maximum Transient Thermal Impedance

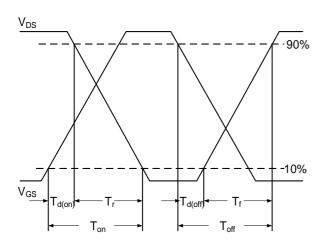


Fig.10 Switching Time Waveform

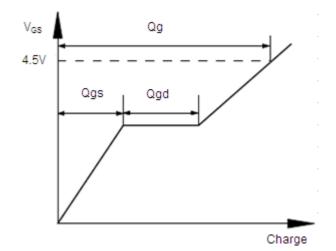
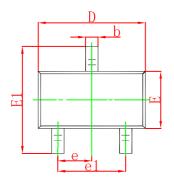
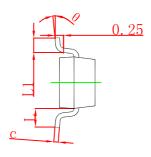


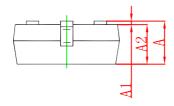
Fig.11 Gate Charge Waveform



SOT-23 Package Outline Dimensions

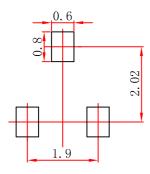






Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
Е	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

SOT-23 Suggested Pad Layout



- Note:
 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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